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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10058650	FILING DATE 01/28/2002	CLASS 289	SUBCLASS E25	GAU 3729	EXAMINER DH [Signature]
**APPLICANTS: Chen Shih-Hui; Field Cheryl; Lefebvre Didier; Wang Joe; <div style="text-align: center;">DN</div>					
**CONTINUING DATA VERIFIED: <div style="text-align: center;">DN</div>					
** FOREIGN APPLICATIONS VERIFIED: <div style="text-align: center;">none DN</div>					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials [Signature]		AP01985			
TITLE : Method of separating and handling a thin semiconductor die on a wafer					
<small>U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)</small>					

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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